



Material Content Data Sheet



Sales Product Name		TLE6251-2G		Issued		19. July 2018		
MA#		MA001465868						
Package		PG-DSO-14-1		Weight*		143.62 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.050	3.52	3.52	35162	35162
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105	
	non noble metal	zinc	7440-66-6	0.060	0.04		420	
	non noble metal	iron	7439-89-6	1.207	0.84		8404	
wire	non noble metal	copper	7440-50-8	49.007	34.12	35.01	341236	350165
	noble metal	gold	7440-57-5	0.206	0.14	0.14	1436	1436
	encapsulation	organic material	carbon black	1333-86-4	0.168	0.12		1168
plastics	plastics	epoxy resin	-	7.717	5.37		53736	
		silicondioxide	60676-86-0	75.999	52.93	58.42	529179	584083
leadfinish	non noble metal	tin	7440-31-5	1.241	0.86	0.86	8644	8644
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7170	7170
glue	plastics	acrylic resin	-	0.421	0.29		2935	
		noble metal	silver	7440-22-4	1.494	1.04	1.33	10405
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com